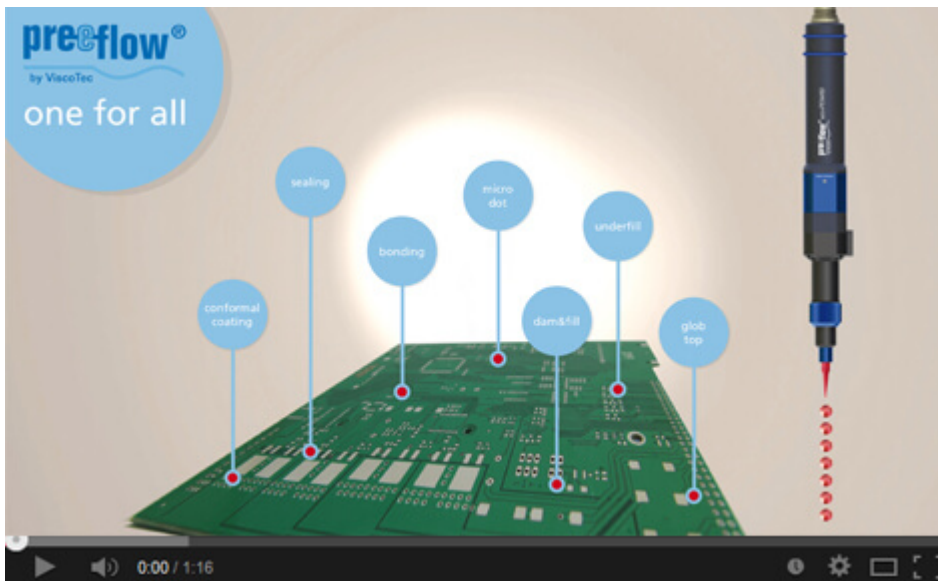


preflow micro-dispensing for electronics manufacturing

Description

We have previously discussed [the need for greater precision and repeatability of adhesive dispensing](#) within ever smaller and denser pcb real estate in the world of electronics assembly and manufacturing. Applications include optical bonding (e.g. touch screens, displays, smartphones, tablets), conformal coating, encapsulation (either dam & fill or glob top), underfills, and the like. There are many other applications where micro-dispensing (amounts of less than a few microlitres) of adhesives or protective materials is needed.

[Here is a video which explains more!](#)



preeflow micro-dispensing for electronics manufacturing

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